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FORM PTO-1595  
(Rev. 6-93)  
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U.S. Department of Commerce  
Patent And Trademark Office

101721891

To the Honorable Commissioner of

attached original document or copy thereof.

1. Name of conveying party(ies):  
Naotomi Takahashi  
Yutaka Hirasawa

5-1401

Additional name(s) of conveying party(ies) attached?  
 Yes  No

3. Nature of conveyance:  
 Assignment  Merger  
 Security Agreement  Change of Name  
 Other

Execution Date: January 25, 2001

2. Name and address of receiving party(ies):  
Name: Mitsui Mining & Smelting Co., Ltd.  
Internal Address: \_\_\_\_\_  
Street Address: A11-1 Osaki 1-chome, Shinjogawa-ku  
City: Tokyo  
State: \_\_\_\_\_ Zip: 141-8584  
Country: Japan  
Additional name(s) & address(es) attached?  Yes  No

4. Application number(s) or registration number(s): 09/755,772  
If this document is being filed together with a new application, the execution date of the application is \_\_\_\_\_  
A. Patent Application No.(s) \_\_\_\_\_  
B. Patent No.(s) \_\_\_\_\_

Additional numbers attached?  Yes  No

5. Name and address of party to whom correspondence concerning document should be mailed:  
Name: Harold N. Wells  
Internal Address: Jenkins & Gilchrist  
1445 Ross Avenue - Suite 3200  
City: Dallas State: TX Zip: 75202-2799

6. Total number of applications and patents involved 1  
7. Total fee (37 C.F.R. 3.41) \$ 40.00  
 Enclosed  
 Authorized to be charged to deposit account  
8. Deposit account number: 10-0447/47163-00032  
(Attach duplicate copy of this page if paying by deposit account)

DO NOT USE THIS SPACE

9. Statement and signature.  
*To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.*

Harold N. Wells  
Name of Person Signing

Harold N. Wells  
Signature

5/10/01  
Date

Total number of pages including cover sheet, attachments and document: 3

15-03/2001 LABELS (0600181 0975572)  
Chicago 166365v1 47163-00032

**ASSIGNMENT**

WHEREAS, We, **NAOTOMI TAKAHASHI** and **YUTAKA HIRASAWA** have invented certain new and useful improvements in the following: **ELECTRODEPOSITED COPPER FOIL, METHOD OF INSPECTING PHYSICAL PROPERTIES THEREOF, AND COPPER-CLAD LAMINATE EMPLOYING THE ELECTRO-DEPOSITED COPPER FOIL** for which we have made application for United States Letters Patent; and,

WHEREAS, **MITSUI MINING & SMELTING CO., LTD.**, a corporation organized and existing under the laws of **Japan**, having its principal place of business at **A11-1 Osaki 1-chome, Shinagawa-ku, Tokyo, 141-8584 Japan** (hereinafter referred to as "ASSIGNEE"), is desirous of acquiring our entire right, title and interest in and to the invention, and in and to the said application and any Letters Patent that may issue thereon;

**NOW, THEREFORE**, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, we do hereby sell, assign and transfer unto ASSIGNEE, its successors, assigns and legal representatives the entire right, title and interest in and to said invention and in and to said applications and all patents which may be granted therefore, and all provisionals, divisions, reissues, substitutions, continuations, continuation-in-part and extensions thereof; and we hereby authorize and request the Commissioner of Patents and Trademarks to issue all patents for said invention, or patents resulting therefrom, insofar as our interest is concerned, to the said ASSIGNEE of our entire right, title and interest.

We also hereby sell and assign to said ASSIGNEE, its successors, assigns and legal representatives the full and exclusive rights, title and interest to the invention disclosed in said applications throughout the world, including the right to file applications and obtain patents, utility models, industrial models and designs for said invention in its own name throughout the world including all rights of priority, all rights to publish cautionary notices reserving ownership of said invention and all rights to register said invention in appropriate registries; and

We further agree to execute any and all powers of attorney, applications, assignments, declarations, affidavits, and any other papers in connection therewith necessary to perfect such rights, title and interest in ASSIGNEE, its successors, assigns and legal representatives.

We hereby further agree that we will communicate to said ASSIGNEE, or its successors, assigns and legal representatives, any facts known to us respecting any improvements; and, at the expense of said ASSIGNEE, to testify in any legal proceedings, sign all lawful papers, execute all divisional, continuation, continuation-in-part, reissue and substitute applications, make all lawful oaths, and generally do everything possible to vest title in said ASSIGNEE and to aid said ASSIGNEE, its successors, assigns and legal representatives to obtain and enforce proper protection for said invention in all countries.

We further authorize and direct our attorneys to insert below\* the serial number and filing date of said application now identified as Case Docket No. **47163-00032** as soon as the same shall have been made known to them by the United States Patent Office.

\*Serial Number:           **09/755,772**  
Filing Date:               **January 5, 2001**

